

ABSTRACT OF THE DISCLOSURE

The problem is that, since a coplanar ground conductor located immediately below a line conductor is absent near a through conductor for providing connection between the one ends of the line conductors each having the coplanar ground conductor, characteristic impedance mismatch occurs and this leads to poor transmission characteristics. The invention provides a high-frequency wiring board in which, given that the interval between the first/second line conductor and part of the first/second coplanar ground conductor located around each side of the line conductor is S , and that the distance between the first/second line conductor and its corresponding second/first coplanar ground conductor facing each other via the dielectric substrate is H , then the following relationship holds: $S < H/2$. Characteristic impedance matching is achieved in the joint between the first/second line conductor and the through conductor, and satisfactory transmission characteristics are accordingly attained in transmission of a millimeter-wave-band high-frequency signal.